

## **exceet at the SMT Hybrid 2016: AEMtec highlights new developments in wafer processing**

- Much shorter lead times in preparing wafers for flip chip processes

**Rotkreuz, Berlin, April 19, 2016 – AEMtec GmbH, a member company of the technology group exceet and specialist for maximum-quality micro- and opto-electronics, will be on location at this year's SMT Hybrid to showcase ultramodern manufacturing technologies for cleanroom applications.**

AEMtec is a leading provider in the field of module production for optical data transmission, sensors and camera modules in line with the strictest quality specifications. At the SMT Hybrid expo, set to take place in Nuremberg from April 26 to 28, 2016, visitors can gain an impression of AEMtec's new capabilities in the wafer back-end sphere. Thanks to new production facilities, the technology specialist is able to assume new manufacturing steps along the wafer value chain and thus offer its clients much shorter lead times for small and medium production volumes.

### **State of the Art Technologies Satisfy Current Market Demand & Trends**

Additional highlights of expanded production at AEMtec include processing of different wafer types up to 300 mm in diameter and placement on substrate surfaces up to 600 x 550 mm<sup>2</sup>. The company can produce modules for optical data transmission as well as sensors and camera modules with a placement precision of +/- 2.5µm@3sigma. Manufacturers in this industry can only manage high production volumes if they can rely on an integrated, fully automatic substrate handling system – another technology implemented at AEMtec.

### **High Sensor Production Volumes at Attractive Prices**

AEMtec has already been active in this segment since 2008 and thus offers broad competency, wide-ranging manufacturing capabilities and ultra-precise placement. The latest expansion of AEMtec's production facilities in Berlin lets the company offer short lead times even for high production volumes – at attractive pricing.

**Please visit exceet / AEMtec from April 26 - 28, 2016 at the SMT Hybrid Packaging in Nuremberg in Hall 7A / Booth 331A**

AEMtec will be on site at a joint booth with Fraunhofer IZM under the motto "Optics meets Electronics". At a forum to be held in Hall 7, Matthias Lorenz will offer a presentation on high-precision placement and how it can be realized.

**Your Direct Contact at AEMtec:**

Matthias Lorenz – Email: [matthias.lorenz@aemtec.com](mailto:matthias.lorenz@aemtec.com) - Phone +49 160 90747793

**Image material available on request**

**About exceet Group**

exceet is an international technology group specializing in intelligent electronics, complex and reliable electronics.

**About AEMtec GmbH**

AEMtec, with headquarters and manufacturing facilities at the reputable science and technology park Berlin-Adlershof, develops and manufactures high-quality, client-specific micro- and opto-electronic modules. The company possesses state-of-the-art packaging technologies including chip on board, flip chip, 3D integration and opto-packaging. AEMtec's portfolio also extends to wide-ranging development services, e.g. feasibility studies for mounting and bonding technology, design and layout, as well as production of test equipment and support through to serial production.

**Contact**

exceet Group AG  
Riedstrasse 1  
CH-6343 Rotkreuz  
Judith Balfanz, Editorial Director  
Phone +49 (0)211 – 43 69 890  
[judith.balfanz@exceet.ch](mailto:judith.balfanz@exceet.ch) / [www.exceet.ch](http://www.exceet.ch)